

High-Speed CMOS Logic Dual Retriggerable Monostable Multivibrators with Resets

Features

- Overriding Reset Terminates Output Pulse
- Triggering From the Leading or Trailing Edge
- Q and \bar{Q} Buffered Outputs
- Separate Resets
- Wide Range of Output-Pulse Widths
- Schmitt Trigger on Both \bar{A} and B Inputs
- Fanout (Over Temperature Range)
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5V$
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility, $V_{IL} = 0.8V$ (Max), $V_{IH} = 2V$ (Min)
 - CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL} , V_{OH}

Description

The 'HC123, 'HCT123, CD74HC423 and CD74HCT423 are dual monostable multivibrators with resets. They are all retriggerable and differ only in that the 123 types can be triggered by a negative to positive reset pulse; whereas the 423 types do not have this feature. An external resistor (R_X) and an external capacitor (C_X) control the timing and the accuracy for the circuit. Adjustment of R_X and C_X provides a wide range of output pulse widths from the Q and \bar{Q} terminals. Pulse triggering on the \bar{A} and B inputs occur at a particular voltage level and is not related to the rise and fall times of the trigger pulses.

Once triggered, the output pulse width may be extended by retriggering inputs \bar{A} and B. The output pulse can be terminated by a LOW level on the Reset (R) pin. Trailing edge triggering (\bar{A}) and leading edge triggering (B) inputs are provided for triggering from either edge of the input pulse. If either Mono is not used each input on the unused device (\bar{A} , B, and R) must be terminated high or low.

The minimum value of external resistance, R_X is typically 5k Ω . The minimum value external capacitance, C_X , is 0pF. The calculation for the pulse width is $t_W = 0.45 R_X C_X$ at $V_{CC} = 5V$.

Ordering Information

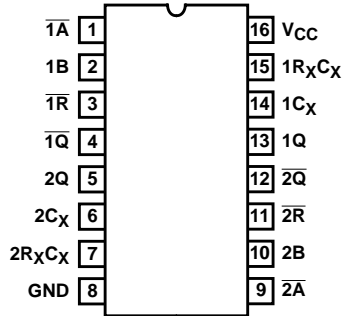
PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC123F3A	-55 to 125	16 Ld CERDIP
CD54HCT123F3A	-55 to 125	16 Ld CERDIP
CD74HC123E	-55 to 125	16 Ld PDIP
CD74HC123M	-55 to 125	16 Ld SOIC
CD74HC123MT	-55 to 125	16 Ld SOIC
CD74HC123M96	-55 to 125	16 Ld SOIC
CD74HC123NSR	-55 to 125	16 Ld SOP
CD74HC123PW	-55 to 125	16 Ld TSSOP
CD74HC123PWR	-55 to 125	16 Ld TSSOP
CD74HC123PWT	-55 to 125	16 Ld TSSOP
CD74HC423E	-55 to 125	16 Ld PDIP
CD74HC423M	-55 to 125	16 Ld SOIC
CD74HC423MT	-55 to 125	16 Ld SOIC
CD74HC423M96	-55 to 125	16 Ld SOIC
CD74HC423NSR	-55 to 125	16 Ld SOP
CD74HCT123E	-55 to 125	16 Ld PDIP
CD74HCT123M	-55 to 125	16 Ld SOIC
CD74HCT123MT	-55 to 125	16 Ld SOIC
CD74HCT123M96	-55 to 125	16 Ld SOIC
CD74HCT423E	-55 to 125	16 Ld PDIP
CD74HCT423MT	-55 to 125	16 Ld SOIC
CD74HCT423M96	-55 to 125	16 Ld SOIC

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

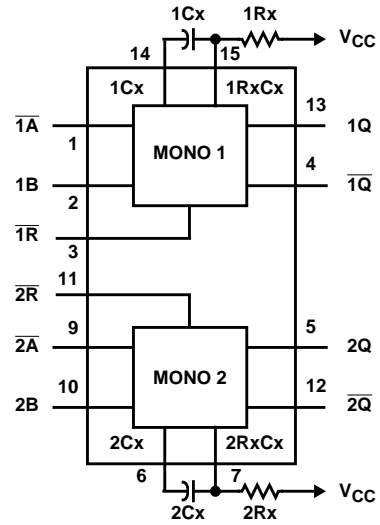
CD54/74HC123, CD54/74HCT123, CD74HC423, CD74HCT423

Pinout

CD54HC123, CD54HCT123
 (CERDIP)
CD74HC123
 (PDIP, SOIC, SOP, TSSOP)
CD74HC423
 (PDIP, SOIC, SOP)
CD74HCT123, CD74HCT423
 (PDIP, SOIC)
 TOP VIEW



Functional Diagram



TRUTH TABLE

INPUTS			OUTPUTS	
\overline{A}	B	\overline{R}	Q	\overline{Q}
CD74HC/HCT123				
H	X	H	L	H
X	L	H	L	H
L	↑	H		
↓	H	H		
X	X	L	L	H
L	H	↑		
CD74HC/HCT423				
H	X	H	L	H
X	L	H	L	H
L	↑	H		
↓	H	H		
X	X	L	L	H

H = High Voltage Level, L = Low Voltage Level,
 X = Don't Care.

CD54/74HC123, CD54/74HCT123, CD74HC423, CD74HCT423

Absolute Maximum Ratings

DC Supply Voltage, V_{CC}	-0.5V to 7V
DC Input Diode Current, I_{IK}	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Diode Current, I_{OK}	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Source or Sink Current per Output Pin, I_O	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$	$\pm 25mA$
DC V_{CC} or Ground Current, I_{CC} or I_{GND}	$\pm 50mA$

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note 1):	
E (PDIP) Package	67°C/W
M (SOIC) Package	73°C/W
NS (SOP) Package	64°C/W
PW (TSSOP) Package	108°C/W
Maximum Junction Temperature	150°C
Maximum Storage Temperature Range	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(SOIC - Lead Tips Only)	

Operating Conditions

Temperature Range (T_A)	-55°C to 125°C
Supply Voltage Range, V_{CC}	
HC Types2V to 6V
HCT Types	4.5V to 5.5V
DC Input or Output Voltage, V_I, V_O	0V to V_{CC}
Input Rise and Fall Time	
2V	1000ns (Max)
4.5V	500ns (Max)
6V	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V_I (V)	I_O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES												
High Level Input Voltage	V_{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V_{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads	V_{OH}	V_{IH} or V_{IL}	-	-	-	-	-	-	-	-	-	V
			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads	V_{OL}	V_{IH} or V_{IL}	-	-	-	-	-	-	-	-	-	V
			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} or GND	-	6	-	-	± 0.1	-	± 1	-	± 1	μA
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	6	-	-	8	-	80	-	160	μA

CD54/74HC123, CD54/74HCT123, CD74HC423, CD74HCT423

DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V _I (V)	I _O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HCT TYPES												
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I _I	V _{CC} and GND	0	5.5	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I _{CC}	V _{CC} or GND	0	5.5	-	-	8	-	80	-	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI _{CC} (Note 2)	V _{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA

NOTE:

- For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
All	0.35

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Table, e.g. 360μA max at 25°C.

Prerequisite for Switching Specifications

PARAMETER	SYMBOL	V _{CC} (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
HC TYPES												
Minimum Input, Pulse Width A	t _{WL}	2	100	-	-	125	-	-	150	-	-	ns
		4.5	20	-	-	25	-	-	30	-	-	ns
		6	17	-	-	21	-	-	26	-	-	ns
B	t _{WH}	2	100	-	-	125	-	-	150	-	-	ns
		4.5	20	-	-	25	-	-	30	-	-	ns
		6	17	-	-	21	-	-	26	-	-	ns

CD54/74HC123, CD54/74HCT123, CD74HC423, CD74HCT423

Prerequisite for Switching Specifications (Continued)

PARAMETER	SYMBOL	V _{CC} (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
\bar{R}	t _{WL}	2	100	-	-	125	-	-	150	-	150	ns
		4.5	20	-	-	25	-	-	30	-	30	ns
		6	17	-	-	21	-	-	26	-	26	ns
\bar{A} and B Hold Time	t _H	2	50	-	-	65	-	-	75	-	75	ns
		4.5	10	-	-	13	-	-	15	-	15	ns
		6	9	-	-	11	-	-	13	-	13	ns
Reset Removal Time	t _{REM}	2	50	-	-	65	-	-	75	-	75	ns
		4.5	10	-	-	13	-	-	15	-	15	ns
		6	9	-	-	11	-	-	13	-	13	ns
Retrigger Time Number R _X = 10KΩ, C _X = 0	t _{rT}	5	-	-	-	-	-	-	-	-	-	ns
			-	50	-	-	63	-	-	76	-	ns
Output Pulse Width Q or \bar{Q} R _X = 10KΩ, C _X = 10nF	t _W	5	40	-	50	38.7	-	51.3	38.2	-	51.8	μs
HCT TYPES												
Minimum Input, Pulse Width \bar{A}	t _{WL}	5	20	-	-	25	-	-	30	-	-	ns
B	t _{WH}		20	-	-	25	-	-	30	-	-	ns
\bar{R}	t _{WL}		20	-	-	25	-	-	30	-	-	ns
\bar{A} and B Hold Time	t _H	5	10	-	-	13	-	-	15	-	-	ns
Reset Removal Time	t _{REM}	5	10	-	-	13	-	-	15	-	-	ns
Retrigger Time Number (Note 3) R _X = 10KΩ, C _X = 0	t _{rT}	5	-	50	-	-	63	-	-	76	-	ns
Output Pulse Width Q or \bar{Q} R _X = 10KΩ, C _X = 10nF	t _W	5	40	-	50	38.7	-	51.3	38.2	-	51.8	μs

NOTE:

- Time to trigger depends on the values of R_X and C_X. The output pulse width can only be extended when the time between the active-going edges of the trigger input pulses meet the minimum retrigger time requirement.

CD54/74HC123, CD54/74HCT123, CD74HC423, CD74HCT423

Switching Specifications Input $t_r, t_f = 6\text{ns}$, $R_X = 10\text{K}\Omega$, $C_X = 0$

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNIT S
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Trigger Propagation Delay \bar{A}, B, \bar{R} to \bar{Q}	t_{PLH}	$C_L = 50\text{pF}$	2	-	-	300	-	375	-	450	ns
			4.5	-	-	60	-	75	-	90	ns
		$C_L = 15\text{pF}$	5	-	25	-	-	-	-	-	ns
		$C_L = 50\text{pF}$	6	-	-	51	-	64	-	76	ns
\bar{A}, B, \bar{R} to \bar{Q}	t_{PHL}	$C_L = 50\text{pF}$	2	-	-	320	-	400	-	480	ns
			4.5	-	-	64	-	80	-	96	ns
		$C_L = 15\text{pF}$	5	-	26	-	-	-	-	-	ns
		$C_L = 50\text{pF}$	6	-	-	54	-	68	-	82	ns
Reset Propagation Delay \bar{R} to \bar{Q} or \bar{Q}	t_{PHL}, t_{PLH}	$C_L = 50\text{pF}$	2	-	-	215	-	270	-	325	ns
			4.5	-	-	43	-	54	-	65	ns
			6	-	-	37	-	46	-	55	ns
Output Transition Time	t_{THL}, t_{TLH}	$C_L = 50\text{pF}$	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Output Pulse Width $R_X = 10\text{K}\Omega, C_X = 10\text{nF}$	-	-	5	-	45	-	-	-	-	μs	
Pulse Width Match Between Circuits In the Same Package $R_X = 10\text{K}\Omega, C_X = 10\text{pF}$	-	-	5	-	± 2	-	-	-	-	-	%
Power Dissipation Capacitance (Note 4)	C_{PD}	$C_L = 15\text{pF}$	5	-	-	-	-	-	-	-	pF
Input Capacitance	C_{IN}	$C_L = 50\text{pF}$	-	10	-	10	-	10	-	10	pF
HCT TYPES											
Trigger Propagation Delay \bar{A}, B, \bar{R} to \bar{Q}	t_{PLH}	$C_L = 50\text{pF}$	4.5	-	-	60	-	75	-	90	ns
		$C_L = 15\text{pF}$	5	-	25	-	-	-	-	-	ns
\bar{A}, B, \bar{R} to \bar{Q}	t_{PHL}	$C_L = 50\text{pF}$	4.5	-	-	68	-	85	-	102	ns
		$C_L = 15\text{pF}$	5	-	27	-	-	-	-	-	ns
Reset Propagation Delay \bar{R} to \bar{Q} or \bar{Q}	t_{PHL}, t_{PLH}	$C_L = 50\text{pF}$	4.5	-	-	48	-	60	-	72	ns
Output Transition Time	t_{THL}, t_{TLH}	$C_L = 50\text{pF}$	4.5	-	-	15	-	19	-	22	ns
Output Pulse Width $R_X = 10\text{K}\Omega, C_X = 10\text{nF}$	-	-	5	-	45	-	-	-	-	-	μs

CD54/74HC123, CD54/74HCT123, CD74HC423, CD74HCT423

Switching Specifications Input $t_r, t_f = 6\text{ns}$, $R_X = 10\text{K}\Omega$, $C_X = 0$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNIT S
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Pulse Width Match Between Circuits In the Same Package $R_X = 10\text{K}\Omega$, $C_X = 10\text{pF}$	-	-	5		± 2	-	-	-	-	-	%
Input Capacitance	C_{IN}	$C_L = 50\text{pF}$	-	-	-	10	-	10	-	10	pF

NOTE:

4. C_{PD} is used to determine the dynamic power consumption, per multivibrator.

$$P_D = (C_{PD} + C_X) V_{CC}^2 f_i \sum (C_L V_{CC}^2 f_O)$$

Where

f_i = input frequency

f_O = Output Frequency

C_L = Output Load Capacitance

C_X = External Capacitance

V_{CC} = Supply Voltage,

assuming $f_i \ll \frac{1}{t_W}$

Test Circuits and Waveforms

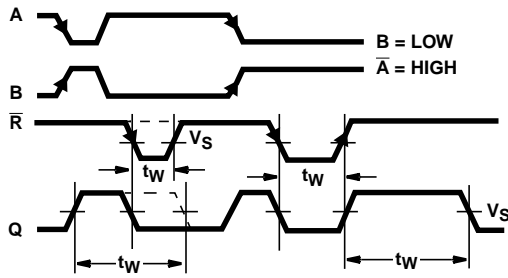


FIGURE 1. OUTPUT PULSE CONTROL USING RESET INPUT (\bar{R}) PULSE FOR 123

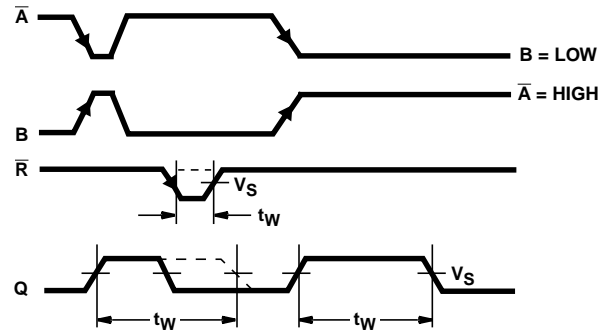
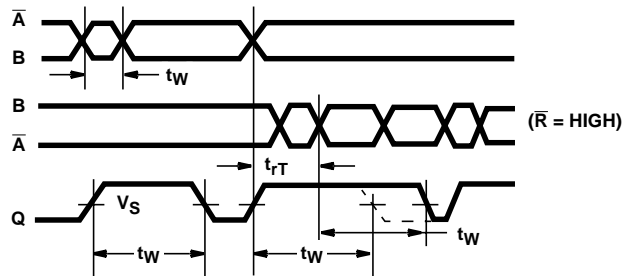


FIGURE 2. OUTPUT PULSE CONTROL USING RESET INPUT (\bar{R}) FOR 423



NOTE: Output pulse control using retrigger pulse for 123 and 423.

FIGURE 3. TRIGGERING OF ONE SHOT BY INPUT \bar{A} OR INPUT B FOR A PERIOD t_w

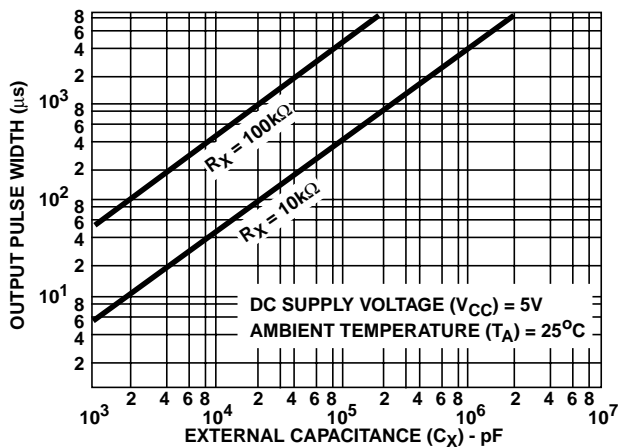


FIGURE 4. TYPICAL OUTPUT PULSE WIDTH AS A FUNCTION OF C_x FOR $R_x = 10k\Omega$ AND $100k\Omega$

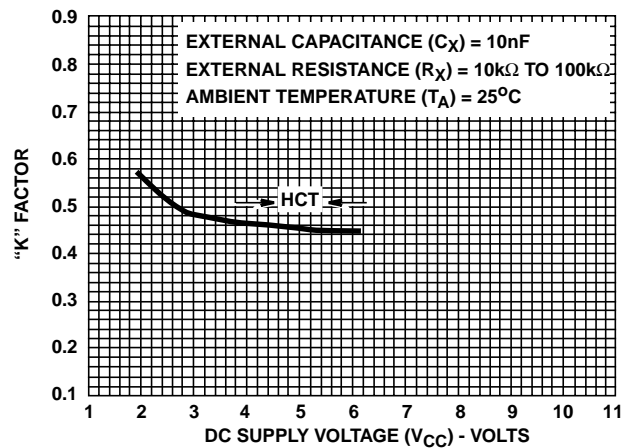


FIGURE 5. TYPICAL "K" FACTOR AS A FUNCTION OF V_{CC}

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-8684701EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
5962-8970001EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
CD54HC123F	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD54HC123F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD54HCT123F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD74HC123E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC123EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC123M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CD74HC123PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC123PWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC423E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC423EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC423M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC423M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC423M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC423M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC423ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC423MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC423MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC423MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC423MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CD74HC423NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC423NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC423NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT123E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HCT123EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HCT123M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT123M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT123M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT123M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT123ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT123MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT123MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT123MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT123MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT423E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HCT423EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HCT423M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT423M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT423M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CD74HCT423MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT423MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT423MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF CD54HC123, CD54HCT123, CD74HC123, CD74HCT123 :

● Catalog: [CD74HC123](#), [CD74HCT123](#)

● Military: [CD54HC123](#), [CD54HCT123](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC123NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC123PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC123PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC423M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC423NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HCT123M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HCT423M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC123NSR	SO	NS	16	2000	367.0	367.0	38.0
CD74HC123PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
CD74HC123PWT	TSSOP	PW	16	250	367.0	367.0	35.0
CD74HC423M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74HC423NSR	SO	NS	16	2000	367.0	367.0	38.0
CD74HCT123M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74HCT423M96	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

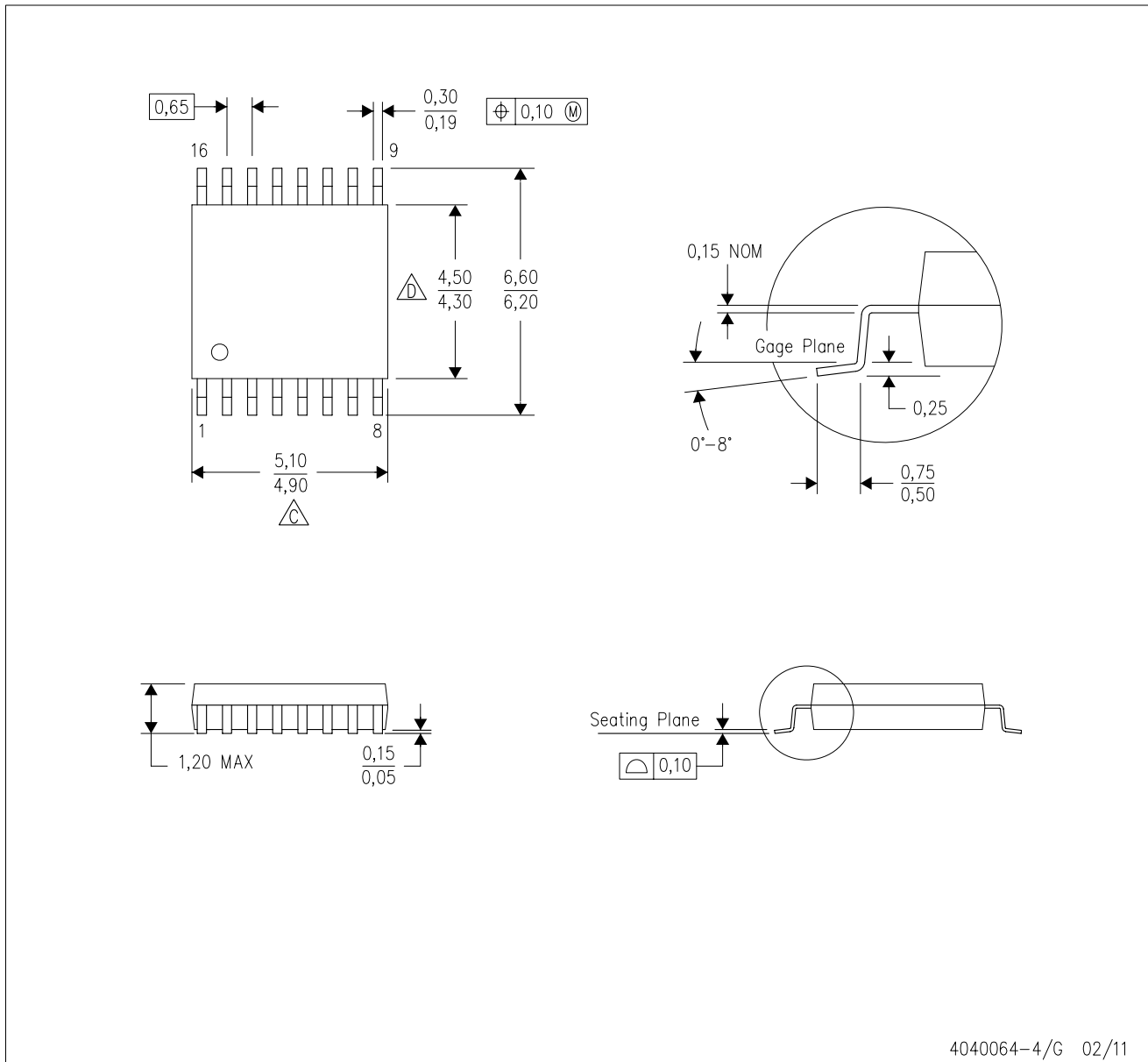


4211283-4/E 08/12



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

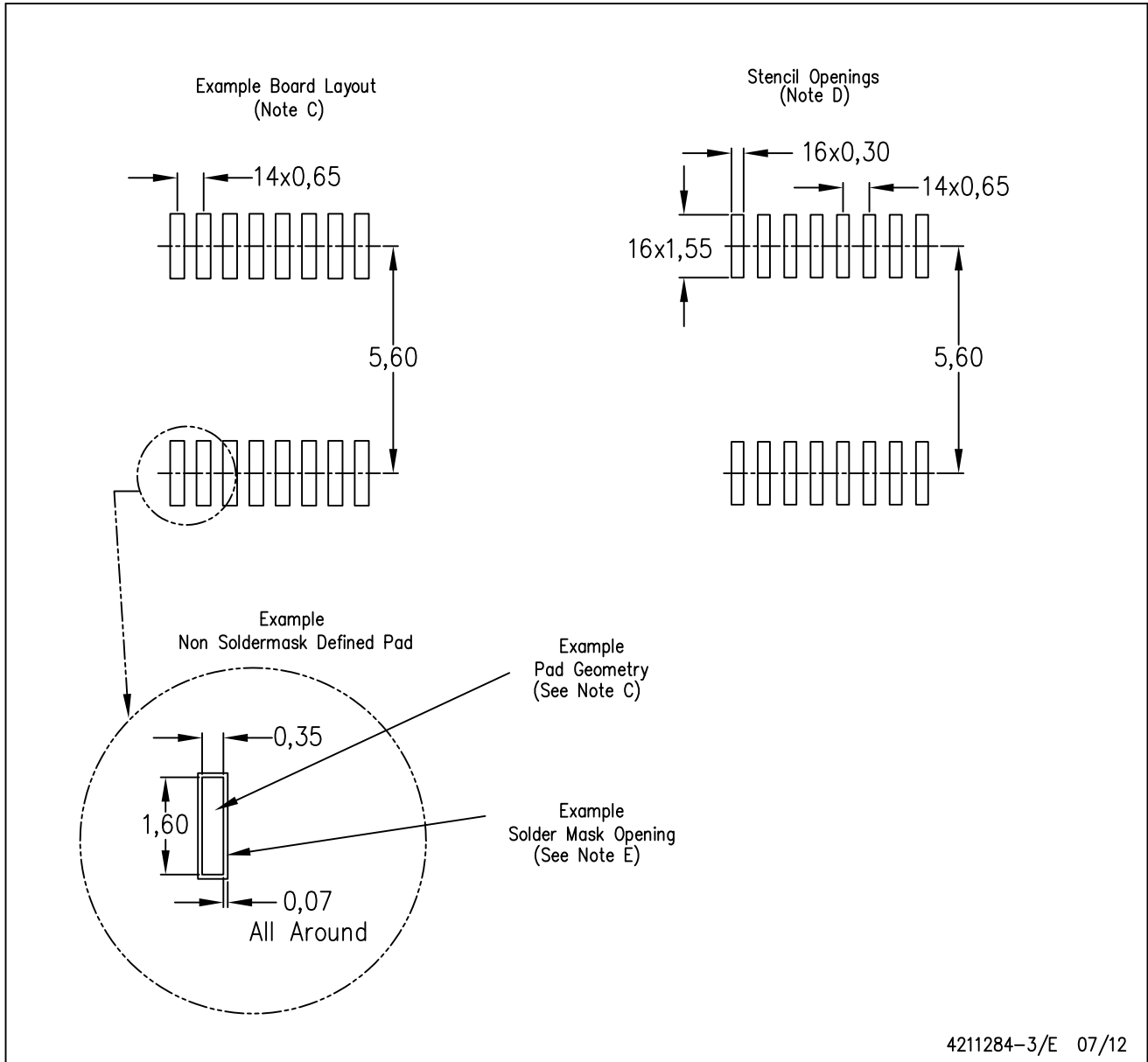


4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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